Product Change Notification: DSNO-02DXZO965

Date:

10-Feb-2025

Product Category:

AC/DC - Inductorless Offline Controllers

Notification Subject:

CCB 7386 Final Notice: Qualification of MMT as new assembly site for SR10LG-G catalog part number (CPN) available in 8L SOIC (3.90mm) package.

Affected CPNs:

DSNO-02DXZO965_Affected_CPN_02102025.pdf
DSNO-02DXZO965_Affected_CPN_02102025.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as new assembly site for SR10LG-G catalog part number (CPN) available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**
Assembly Site	UTAC Thai Limited (UTL-2) (NSEB)	Microchip Technology Thailand (MMT)
Wire Material	Au	Au
Die Attach Material	8200T	8390A

Molding Compound Material	G600	G600
Lead-Frame Material	A194	CDA194

Note: C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying MMT as new assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 31 March 2025 (date code: 2514)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2025					**March 2025**			
Work Week	05	06	07	08	09	10	11	12	13
Qual Report Availability		X							
Final PCN Issue Date		X							
Estimated Implementation Date									X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 10, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-02DXZO965_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

SR10LG-G

QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: DSNO-02DXZO965

Date
June 19, 2021

Qualification of MMT as new assembly site for SR10LG-G catalog part number (CPN) available in 8L SOIC (3.90mm) package. This is a Q100 Grade 0 qualification and will qualify by similarity (QBS).

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as new assembly site for SR10LG-G catalog part number (CPN) available in 8L SOIC (3.90mm) package. This is a Q100 Grade 0 qualification and will qualify by similarity (QBS).
CN	ES350584
QUAL ID	R2001000 Rev. A
MP CODE	VA9027S7XA01
Part No.	MCP1722-3310H/S7X
Bonding No.	BDE-006378 Rev. 01
CCB No.:	4359 and 7386
Package	
Type	8L SOIC-EP
Package size	150 mils
Lead Frame	
Paddle size	95 x 130 mils
Material	A194
Surface	Double Ag Ring Plating
Process	Etched
Lead Lock	No
Part Number	10100847
Treatment	ME-2
Material	
Epoxy	8390A
Wire	Au wire
Mold Compound	G600V
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-213202607.000	TC08921225530.200	2045MSS
MMT-213302511.000	TC08921225530.200	20462UD
MMT-213302512.000	TC08921225530.200	20462UE

Result [X] Pass [ ] Fail [ ] _____

8L SOIC-EP (150 mils) assembled by MMT pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C and 150°C System: ETS-88	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 150°C			0/693	Pass	
Temp Cycle	**Stress Condition:** -55°C to +150°C, 2000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +150°C System: ETS-88		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: ETS-88		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 3.3 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 150°C System: ETS-88		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 1008 hrs System: SHEL LAB **Electrical Test:** +25°C and 150°C System: ETS-88	JESD22-A103	45(0)	45 0/45	Pass	45 units
Power Temperature Cycling	**Stress Condition:** -40°C to +150°C, 1000 Cycles System: Votcsh **Electrical Test:** +25°C and 150°C System: ETS-88	JESD22-A105	45(0)	45 0/45	Pass	45 units
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	30 units
Bond Strength	Wire Pull (> 4.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
Data Assembly	Bond Shear (> 18.00 grams)	CDF-AEC-Q100-001	30 (0) bonds	0/30	Pass	